

HPI

TE Internal #: 3-1734261-3 PCB Mount Header, Right Angle, Wire-to-Board, 3 Position, 1.25 mm [.049 in] Centerline, Partially Shrouded, Nickel, Surface Mount, Signal, HPI

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Connectors > PCB Connectors > PCB Headers & Receptacles > AMP HPI 1.25 mm Headers



Connector System: Wire-to-Board

Number of Positions: 3

Number of Rows: 1

Centerline (Pitch): 1.25 mm [.049 in]

PCB Mount Orientation: Right Angle

All AMP HPI 1.25 mm Headers (100)

Features

Product Type Features

Connector System

Header Type

Wire-to-Board

Partially Shrouded

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Connector Contact Load Condition	Fully Loaded
Number of Positions	3
Number of Rows	1
PCB Mount Orientation	Right Angle
Electrical Characteristics	
Operating Voltage	100 VAC
Body Features	
Primary Product Color	Natural
Contact Features	
PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]

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Contact Layout	Inline
Mating Tab Width	.74 mm[.029 in]
Mating Tab Thickness	.3 mm[.012 in]
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Mating Area Plating Material Finish	Matte
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Nickel
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.3 mm[.012 in]
Terminations per Post (Max)	3
Rectangular Termination Post & Tail Width	.35 mm[.014 in]
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	Without
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	1.25 mm[.049 in]
Dimensions	
Connector Length	9.04 mm[.355 in]
Connector Height	3.45 mm[.136 in]
Connector Width	4.7 mm[.185 in]
Usage Conditions	

Mating Alignment Type	Polarization
Mating Retention	Without
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	1.25 mm[.049 in]
Centerline (Pitch)	
Centerline (Pitch) Dimensions	1.25 mm[.049 in]
Centerline (Pitch) Dimensions Connector Length	1.25 mm[.049 in] 9.04 mm[.355 in]

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Operating Temperature Range	-25 – 85 °C[-13 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	1000
Packaging Type	Reel
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC

Halogen Content

Not Low Halogen - contains Br or Cl > 900 ppm.

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

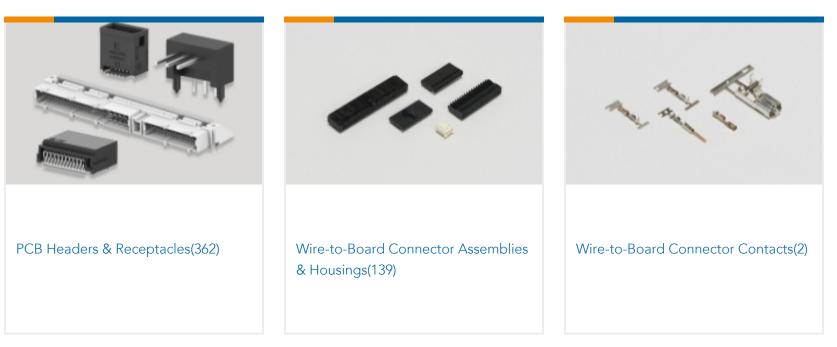
Compatible Parts

PCB Mount Header, Right Angle, Wire-to-Board, 3 Position, 1.25 mm [.049 in] Centerline, Partially Shrouded, Nickel, Surface Mount, Signal, HPI

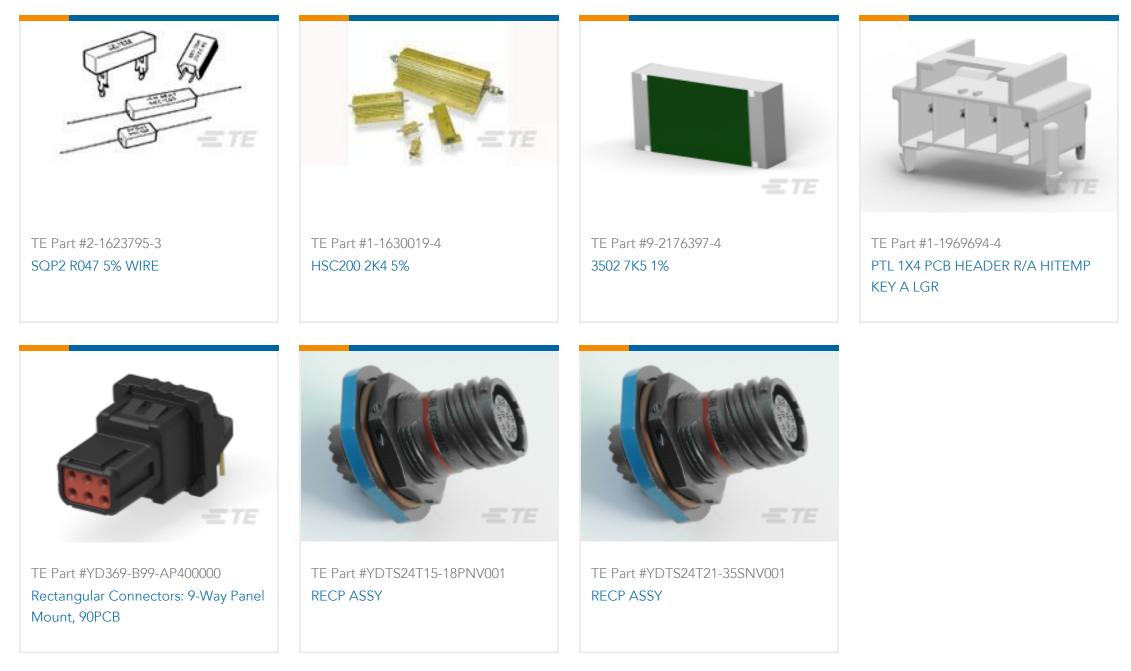




Also in the Series | HPI



Customers Also Bought



Documents

Product Drawings

1.25 WTB PLUG RA 30U" 3 POS

English

CAD Files

Customer View Model ENG_CVM_3-1734261-3_A.3d_igs.zip

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English

Customer View Model ENG_CVM_3-1734261-3_A.3d_stp.zip

English

Customer View Model

ENG_CVM_3-1734261-3_A.2d_dxf.zip

English

3D PDF

English

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Datasheets & Catalog Pages HPI Connectors QRG

English

Product Specifications Application Specification

English